



Description

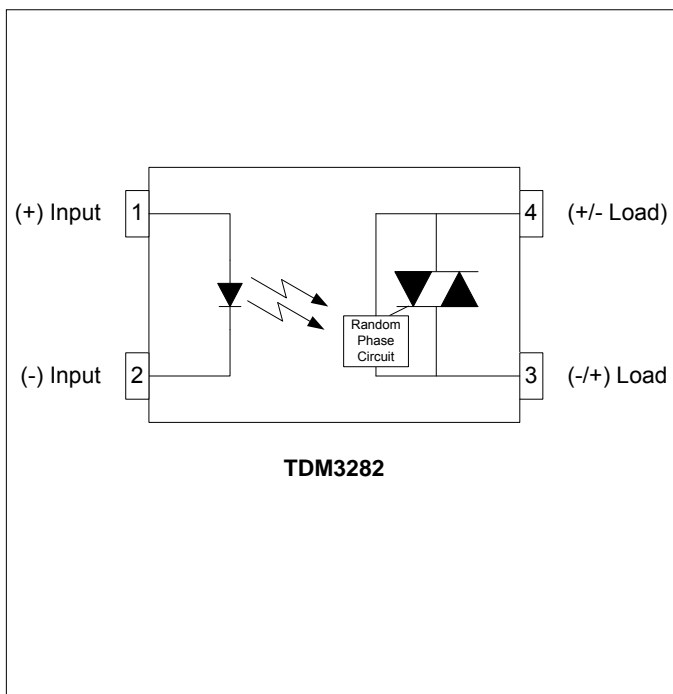
The TDM3282 consists of a GaAs LED optically coupled to a Random Phase photo-sensitive Triac Driver chip. The miniature 4 pin SOP package provides high input-to-output isolation and drives high powered triacs while using very little board space. Typical uses include interfacing logic level control signals to equipment powered from 240V_{AC} lines and higher.

The TDM3282 comes standard in a miniature 4 pin SOP package.

Applications

- Home Appliances
- Motor / Drive Controls
- Solid State Relays
- High Power Triacs
- Dimmer Controls

Schematic Diagram



Features

- Ultra Miniature 4-Pin Small Outline Package
- Random Phase Switching
- 800V Blocking Voltage
- Low Trigger Current (10mA MAX)
- High Input-to-Output Isolation (3.75kV_{RMS})
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL / C-UL: File # E201932
 VDE: File # 40035191 (EN 60747-5-2)

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature-55 to +125°C
 Operating Temperature-40 to +100°C
 Continuous Input Current.....50mA
 Transient Input Current.....500mA
 Reverse Input Control Voltage5V
 Input Power Dissipation.....70mW
 Total Power Dissipation170mW
 Solder Temperature – Wave (10sec).....260°C
 Solder Temperature – IR Reflow (10sec).....260°C

Ordering Information

Part Number	Description
TDM3282	4 pin SOP, (100/Tube)
TDM3282-TR	4 pin SOP, Tape and Reel (2000/Reel)

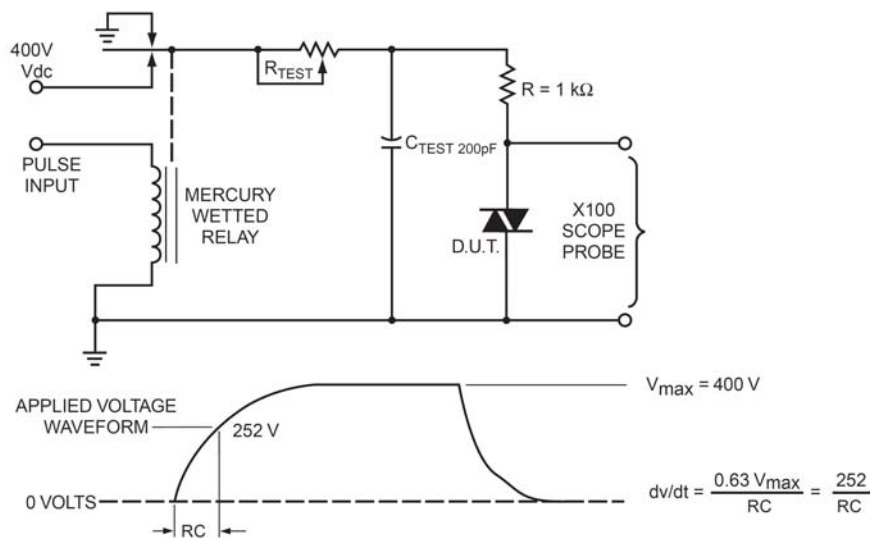
NOTES: Suffixes listed above are not included in marking on device for part number identification

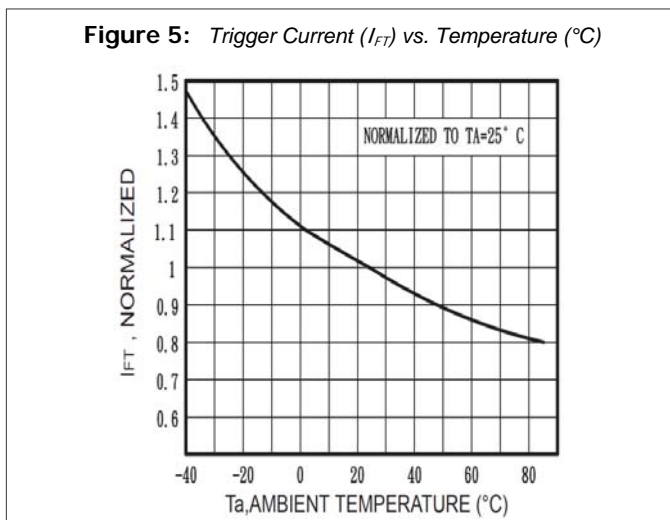
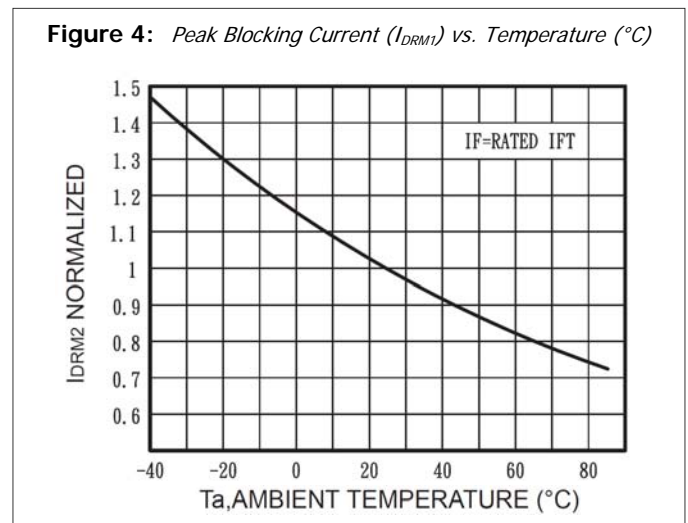
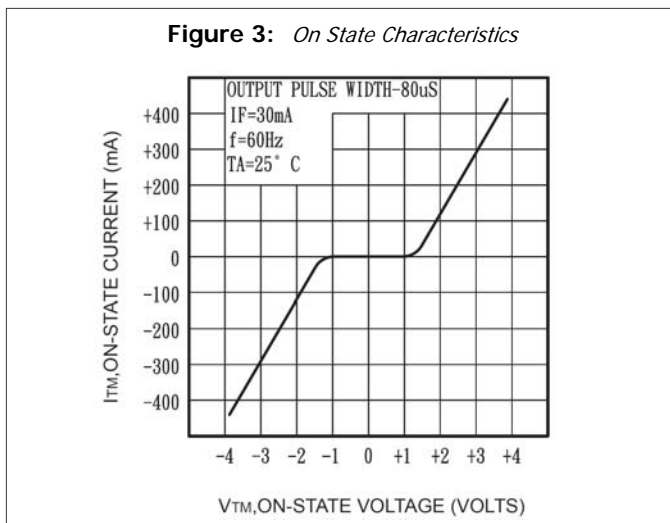
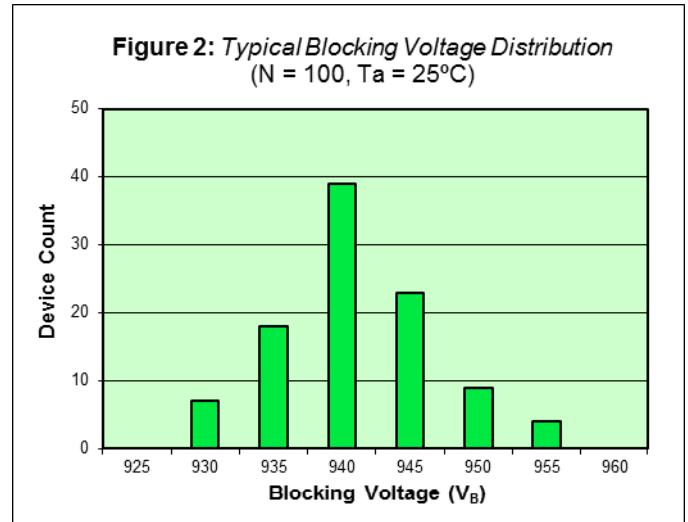
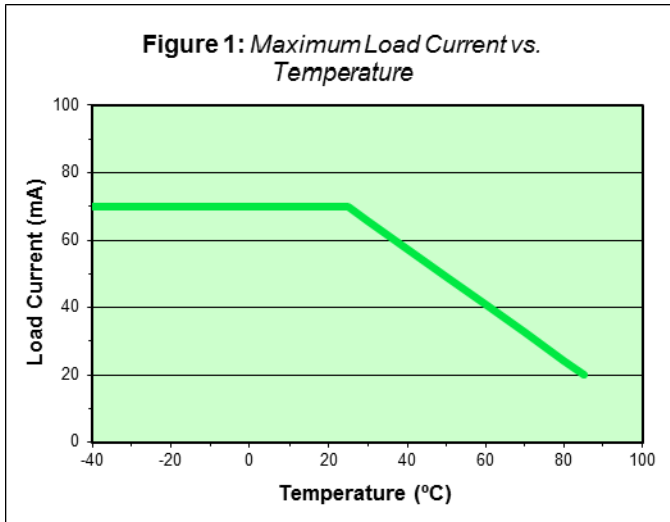
Electrical Characteristics, $T_A = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Specifications						
LED Forward Voltage	V_F	-	1.4	1.8	V	$I_F = 10\text{mA}$
LED Reverse Voltage	BV_R	5	-	-	V	$I_R = 10\mu\text{A}$
Reverse Leakage Current	$I_{InRleak}$	-	-	10	μA	$V_R = 5\mu\text{A}$
Trigger Current ¹	I_{FT}	-	-	10	mA	Main Terminal Voltage = 3V
Output Specifications						
Blocking Voltage	V_{DRM}	800	-	-	V	$I_O = 1\mu\text{A}$
Peak Blocking Current	I_{DRM1}	-	10	100	nA	$V_{DRM} = 800$
Continuous Load Current	I_O	-	-	70	mA	$I_F = 10\text{mA}$
On-State Voltage	V_{ON}	-	2	3	V	$I_F = 10\text{mA}, I_{TM} = 70\text{mA}$
Leakage Current	I_{DRM2}	-	0.2	1	μA	$I_F = 0\text{mA}, V_{DRM} = 800\text{V}$
Holding Current	I_{HOLD}	-	250	-	μA	-
Critical Rate of Rise ²	dV/dt	1,000	1,500	-	$\text{V}/\mu\text{S}$	-
Isolation Specifications						
Isolation Voltage	V_{ISO}	3,750	-	-	V_{RMS}	$RH \leq 50\%, t=1\text{min}$
Input-Output Resistance	R_{I-O}	-	10^{12}	-	Ω	$V_{I-O} = 500V_{DC}$

Note 1: Resistive load. For inductive loads, higher drive current is recommended

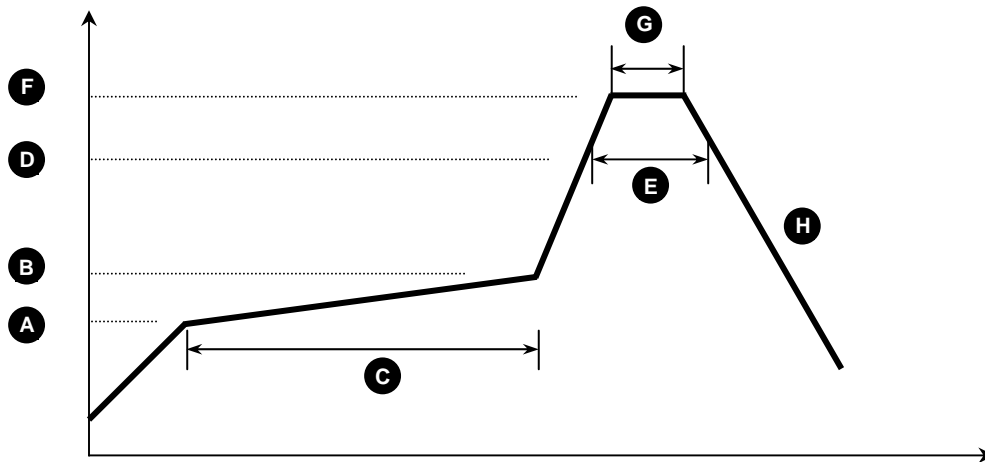
Note 2: This is for static dV/dt . Test Circuit Below

TDM3282 Static dV/dt Test Circuit:


TDM3282 Performance & Characteristics Plots, $T_A = 25^\circ\text{C}$ (unless otherwise specified)


TDM3282 Solder Reflow Temperature Profile Recommendations
(1) *Infrared Reflow:*

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250°C:



Process Step	Description	Parameter
A	Preheat Start Temperature (°C)	150°C
B	Preheat Finish Temperature (°C)	180°C
C	Preheat Time (s)	90 - 120s
D	Melting Temperature (°C)	230°C
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (°C)	260°C
G	Dwell Time at Peak Temperature (s)	10s
H	Cool-down (°C/s)	<6°C/s

(2) *Wave Solder:*

Maximum Temperature: 260°C (at terminal)
 Maximum Time: 10s
 Pre-heating: 100 - 150°C (30 - 90s)
 Single Occurrence

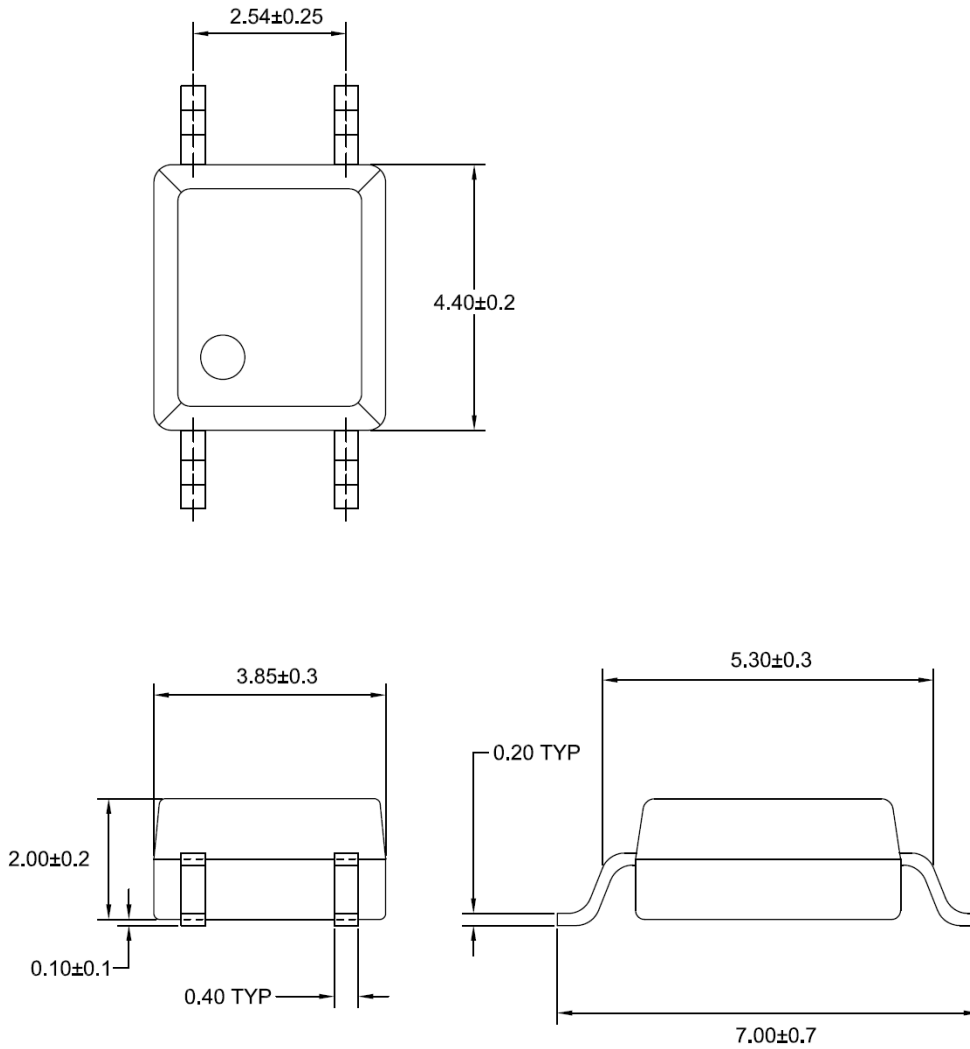
(3) *Hand Solder:*

Maximum Temperature: 350°C (at tip of soldering iron)
 Maximum Time: 3s
 Single Occurrence

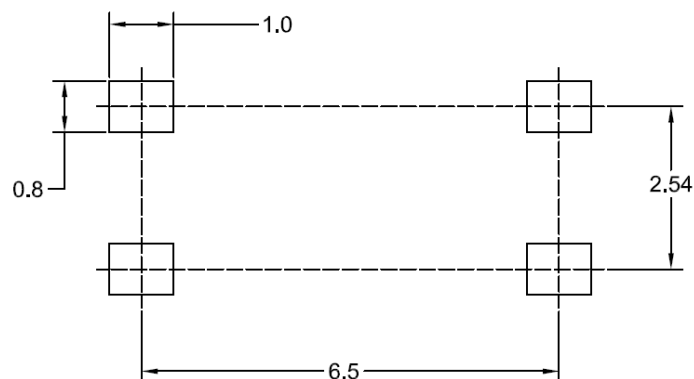
TDM3282 Package Dimensions

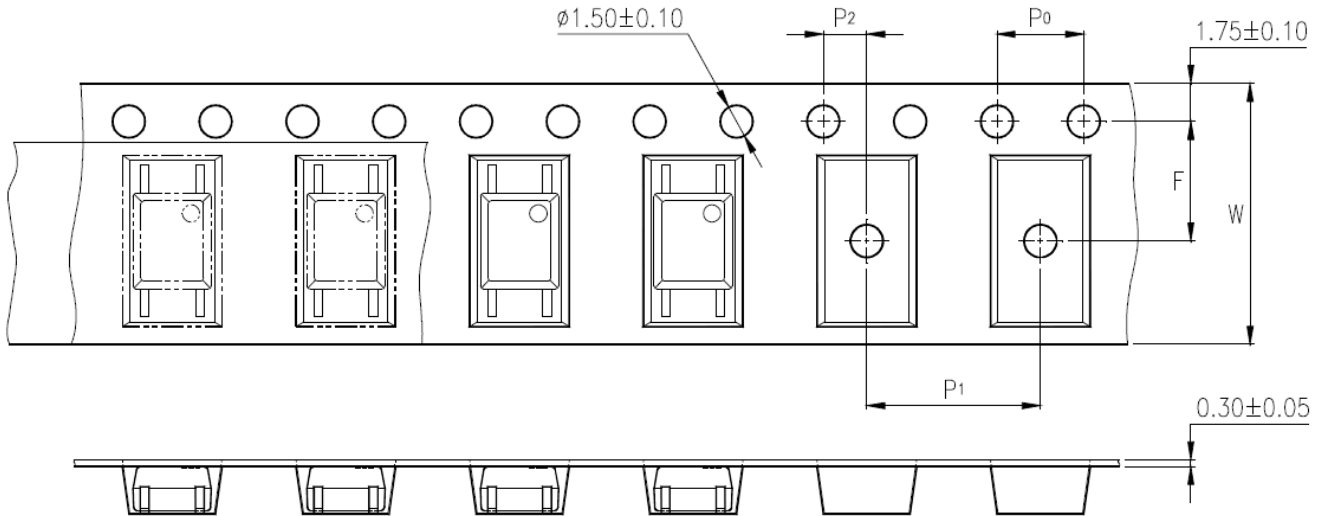
4 PIN SOP Package

Note: All dimensions in millimeters [mm]



4 PIN SOP Footprint



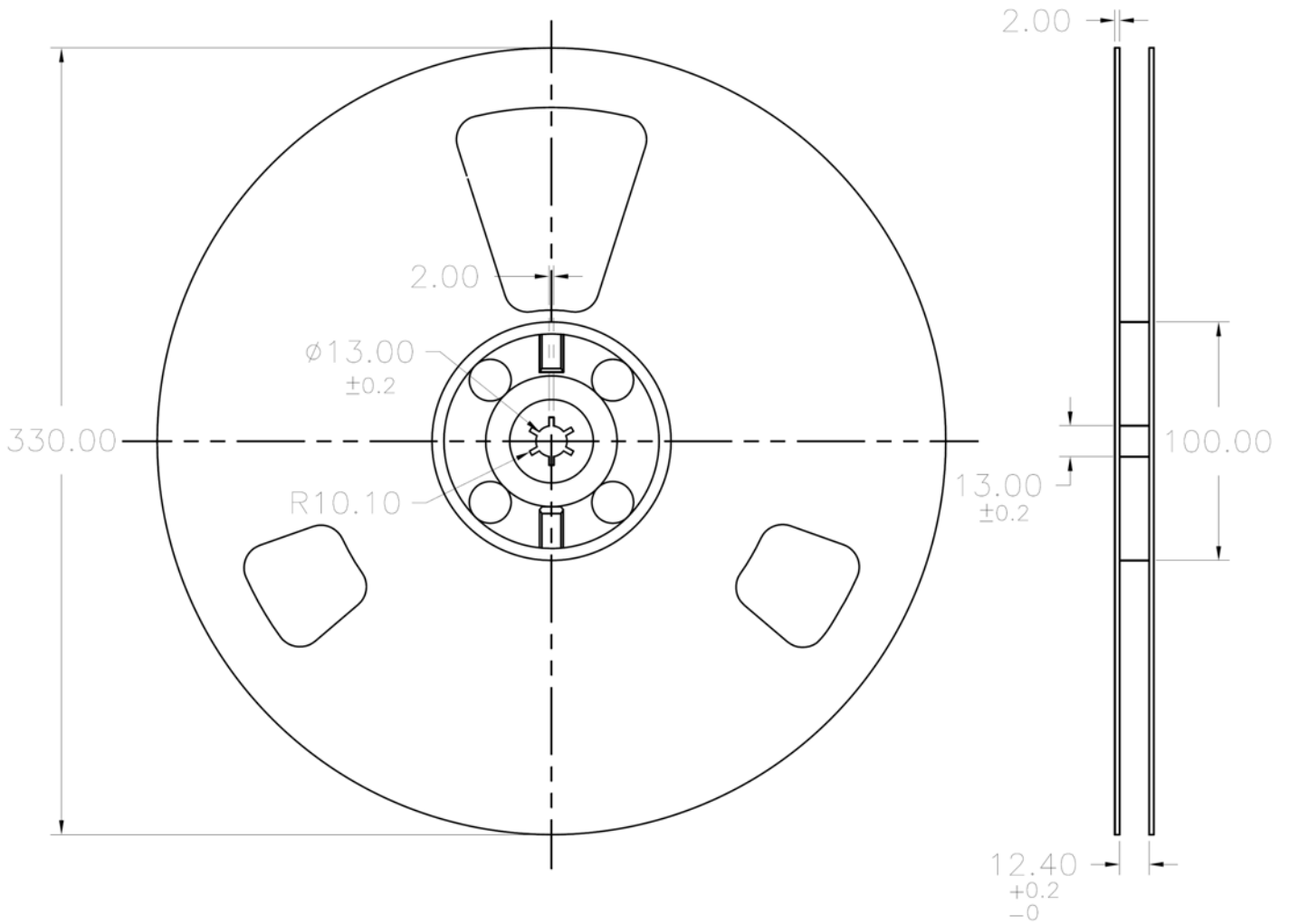
TDM3282 Packaging Specifications
Tape & Reel Specifications (T&R)
Note: All dimensions in millimeters [mm]


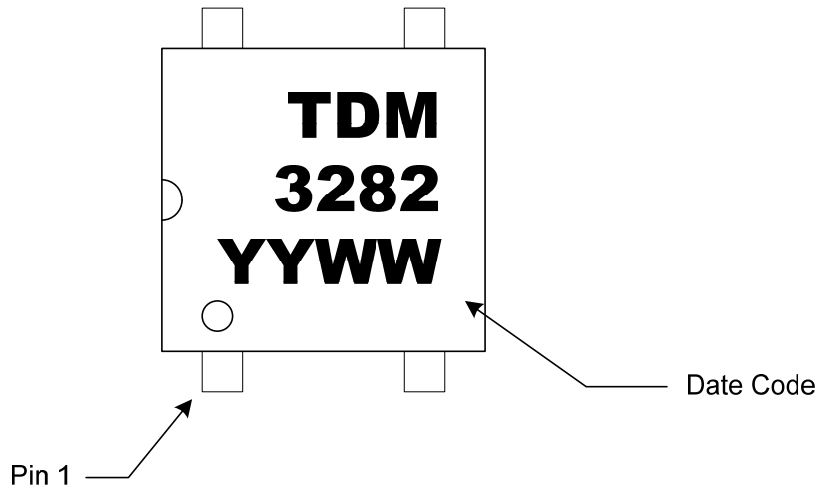
Specification	Symbol	Dimensions, mm (inches)
Tape Width	W	12 ± 0.3 (0.47)
Sprocket Hole Pitch	P0	4 ± 0.1 (0.15)
Compartment Location	F P2	5.5 ± 0.1 (0.217) 2 ± 0.1 (0.079)
Compartment Pitch	P1	8 ± 0.1 (0.315)

TDM3282 Packaging Specifications

Tape & Reel Specifications (T&R)

Note: All dimensions in millimeters [mm]



TDM3282 Package Marking

TDM3282 Package Weights

Device	Single Unit	Full Tube (100pcs)	Full Pouch (10 tubes)	Full Reel (2000pcs)
TDM3282	0.10	23	240	-
TDM3282-TR	0.10	-	-	500

Note: All weights above are in GRAMS, and include packaging materials where applicable

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